



Product Change Notification

Change Notification #: 116020 - 01
Change Title: Intel® RAID Module RMS3CC080,
Intel® RAID Module RMS3CC040,
PCN 116020-01, Product Design,
Stand-offs Upgrade and Firmware Upgrade
**Reason for Revision: Update FW package
version from (MR 6.12 P2) to (MR 6.11 P2)**
Date of Publication: February 02, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:*	January 25, 2018
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Reason for Revision: Update FW package version from (MR 6.12 P2) to (MR 6.11 P2)

Intel is implementing the following changes on the Intel® RAID Modules RMS3CC080 and RMS3CC040:

- Upgrade the stand-offs (they now include a pull tab to make removal easier) and upgrade the controller's firmware to package version 24.15.0-0034 (MR 6.11 P2).

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from this change. Customers may need to validate the function and feature change once the post-change system is available.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
RMS3CC040	932473	H17953-005	H24095-302	H17953-006	H24095-303
RMS3CC080	932474	H17954-005	H24096-302	H17954-006	H24096-303

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
January 10, 2018	00	Originally Published PCN
February 02, 2018	01	Update FW package version from (MR 6.12 P2) to (MR 6.11 P2)



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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